Standardized Information for Process/Product Change Notification (PCN)

1. PCN basic data			
1.1 Company	TAIWAN SEMICONDUCTOR	TAIWAN SEMICONDUCTOR CO.,LTD	
1.2 PCN No.		PCN20010	
1.3 Title of PCN		TO-92 package of plating process changed from DIP soldering to electroplating process	
1.4 Product Category		Active Components - Discrete Components	
1.5 Issue date		2020/10/20	
1.6 PCN revision history (optional)		1.7 Issue date of previous revision (optional)	1.8 Delta to previous revision (optional)

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	Sunnie Lin	
2.1.2 Phone	+886-2-8913-1588 Ext:2205	
2.1.3 Email	sunnie.lin@mail.ts.com.tw	
2.2 Team supplier (optional)		
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)
Chris Lin	+886 2 89131588 Ext.2406	chris_lin@mail.ts.com.tw

3. Changes			
No.	3.0 Ident	3.1 Category	3.2 Type of change
#1	SEM-PA-14	PROCESS - ASSEMBLY	Change in process technology (e.g. sawing, die attach, bonding, moulding, plating, trim and form, lead frame preperation, …)
#2	SEM-EQ-01	EQUIPMENT	Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product

4. Description of change		
	Old	New
Change #1	Dip soldering	Electroplating process
Change #2	self-made manual line, equipment NO.: DT-108、DT-208	high-speed plating line, type NO.: SYUNDAI-001
4.1 Anticipated impact on form, fit, function, reliability or processability?	No impact on form, fit, function, processability and reliability	
4.2 Reference parts with customer number (optional)		

5. Reason / motivation for change	
5.1 Motivation	Improve to satisfy local government environmental regulation
5.2 Additional explanation (optional)	

6. Marking of parts / traceability of change	
6.1 Description	Use date code to trace the change

7. Timing / schedule		
7.1 Date of qualification results	**2020/06/19**	
7.2 Last order date (optional)	**2021/04/18**	
7.3 Last delivery date (optional)	**2022/04/18**	
7.4 Intended start of delivery	**2021/01/18**	
7.5 Qualification samples available?	When get customer order and after 2 weeks can be submitted	
7.6 Customer feedback required until	**2020/12/04**	

8. Qualification / validation				
8.1 Description (e.g. qual. plan/report, AEC-Q...)	According to JESD22			
8.2 Qualification report and qualification results	available (see attachement)	**issue date**	**2020/06/19**	

9. Input to customer for risk assessment process
Human Resource : Low Risk Equipment : Low Risk Technique-Wafer : Low Risk Technique-Assembly : Low Risk Form/ Fit / Function : Low Risk Reliability : Low Risk

10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)
Refer to the official e-mail announcement for the applicable documents.

11. Affected parts									
11.1 Current						11.2 New (if applicable)			
11.1.1 Customer Part No.	**11.1.2 Supplier Part Name**	**11.1.3 Supplier Part No. (optional)**	**11.1.4 Package Name**	**11.1.5 Part Description (optional)**	**11.1.6 Additional Part Information (optional)**	**11.2.2 Supplier Part Name**	**11.2.3 Supplier Part No. (optional)**	**11.2.4 Package Name**	**11.2.6 Additional Part Information (optional)**
